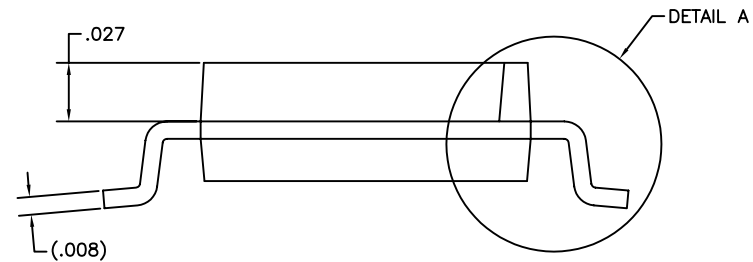
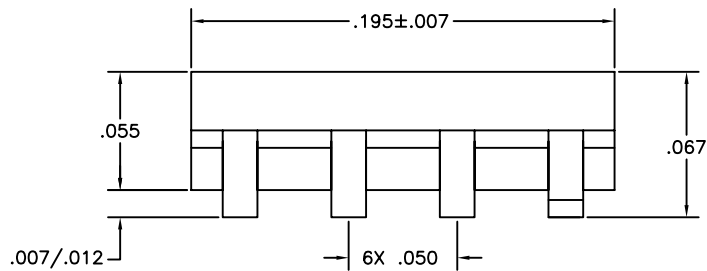
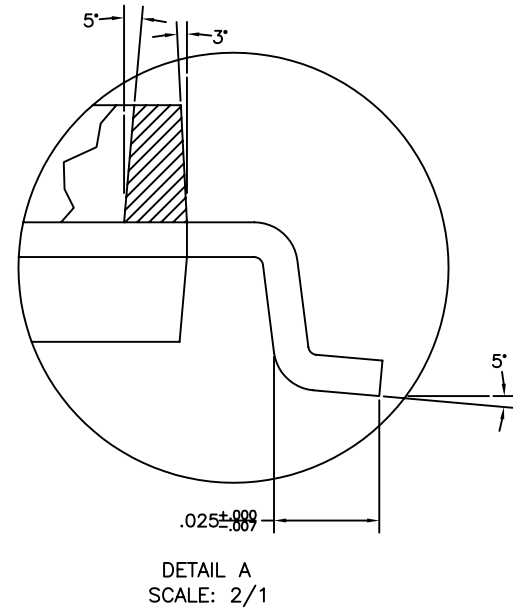
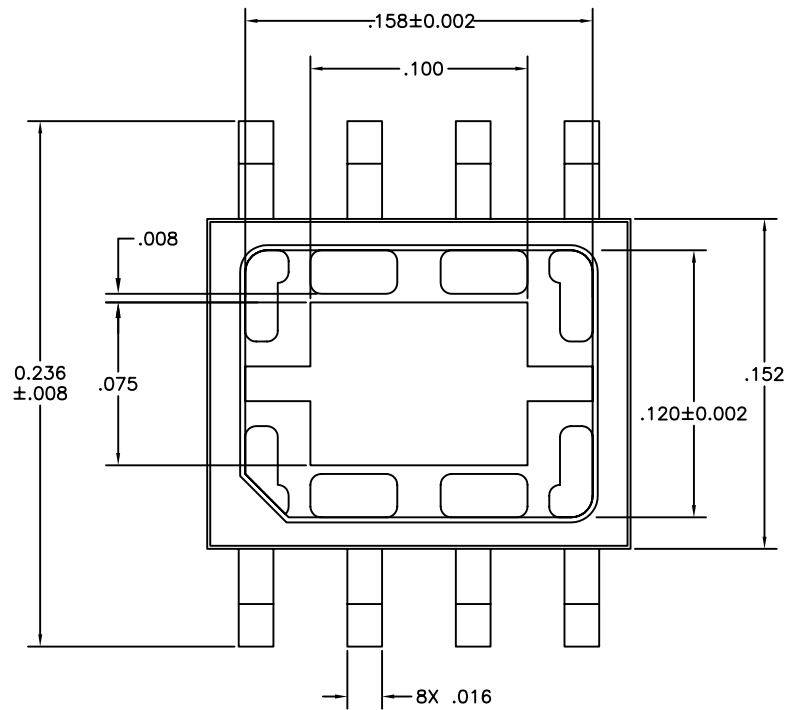


2

1

REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10788	11/01/06	PRODUCTION RELEASE	D.BENANDO



NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEADFRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL Au PLATE.
4. FRAME THICKNESS: .0080±.0003.
5. JEDEC OUTLINE: MS-012.

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
X.XX ± 0.01 X.XXXX ± ---
X.XXX ± 0.005 ANGLES: ± 1'

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	11/01/06
APP BY	P. FLASKERUD	DATE	11/01/06
CUSTOMER	---		
THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO SEMPAC, INC., AND REPRODUCTION OR ISSUE IN ANY FORM IS NOT PERMITTED WITHOUT WRITTEN AUTHORITY FROM SEMPAC, INC.			

SEMPAC, INC.
Open-Pak™ Technologies
www.sempac.com
568 E. WEDDELL DRIVE, SUITE 5
SUNNYVALE, CALIFORNIA 94089
PHONE: (408) 400-9002 FAX: (408) 400-9006

8 Lead 150 mils
SOIC Open-Pak

SIZE	PART NO.	REV
A	SOIC150-08-0P-01	3
SCALE	CAD FILE	SHEET
NONE	SOIC150-08-0P-01-R3.DWG	1 OF 1

2

1